# **ON Semiconductor**



#### INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION Generic Copy

#### 28-Jul-2008

#### SUBJECT: ON Semiconductor Initial Product/Process Change Notification #IPCN16137

# TITLE: Initial Notification of Qualification of Gresham Wafer Fab for NLAS5223BMNR2G and NLAS5223BMUR2G

PROPOSED FIRST SHIP DATE: 10-Dec-2008

AFFECTED CHANGE CATEGORY: ON Semiconductor Wafer Fab Site

#### AFFECTED PRODUCT DIVISION: Analog Switch

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:** Contact Sales Office or Kathleen Van Tyne <<u>k.vantyne@onsemi.com</u>>

# NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

### **DESCRIPTION AND PURPOSE:**

This Initial PCN # 16137 is to announce that ON Semiconductor will be adding wafer fabrication capability at their Gresham, Oregon facility for analog switch devices. These devices will continue to be qualified at the Tower wafer foundry (Israel). Product may begin to ship using die fabricated in the Gresham factory or the Tower foundry at the expiration of the FPCN.

The Gresham wafer fab is ISO9001:2000 compliant. Device performance will be the same among the qualified facilities. All devices will continue to be assembled and tested in existing, qualified locations. No changes to packaging will occur as a result of this capacity expansion qualification.

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# **QUALIFICATION PLAN:**

Test High Temp Op Life(HTOL) Pre-Conditioning (PC) PC + Autoclave (PC+AC) PC + Unbiased HAST (PC+UHAST) PC + Temp Cycle (PC+TC) ESD

Latch Up PC + SAT Electrical Distribution Conditions 150C/504hrs MSL 1, 260C 121C/15psig/96hrs 130C/85%RH/96hrs/No Bias -65C/+150C/500 cyc Human Body Model / Machine Model Dynamic Latch Up MSL 1, 260C Preconditioning ON Semi Spec

## **AFFECTED DEVICE LIST:**

# PART

NLAS5223BMNR2G NLAS5223BMUR2G